

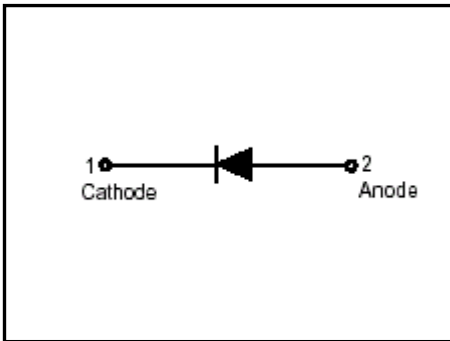
High Speed Switching diode

1SS400C2

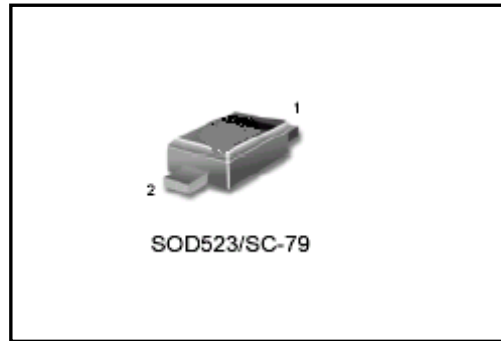
Features

- Extremely small surface mounting type.(SC-79/SOD523)
- High speed switching applications
- Low reverse current

Symbol



Outline



Ordering Information

Device	Package	Shipping
1SS400C2-0-T5-G	SOD-523 (Pb-free lead plating and halogen-free package)	8000 pcs / tape & reel

- ↑ Environment friendly grade : S for RoHS compliant products, G for RoHS compliant and green compound products
- ↑ Packing spec, T5 : 8000 pcs / tape & reel, 7" reel
- ↑ Product rank, zero for no rank products
- ↑ Product name



Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature Tstg..... -55~+150°C
Junction Temperature Tj +150°C
- Maximum Voltages and Currents (Ta=25°C)
DC Reverse Voltage VR 100 V
Mean Rectifying Current IF 200mA
Peak Forward Surge Current IFSM..... 500mA
- Thermal Characteristics
Total Device Dissipation @ TA=25°C (Note) Pd.....200mW
Thermal Resistance, Junction to Ambient RθJA.....625°C/W

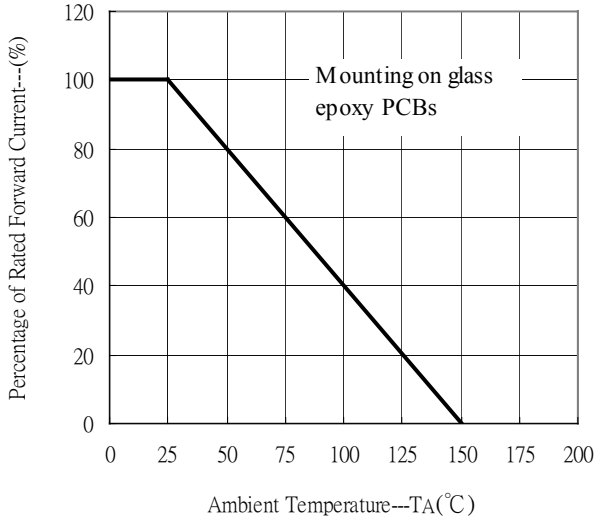
Note: FR-5 board minimum pad.

Characteristics (Ta=25°C)

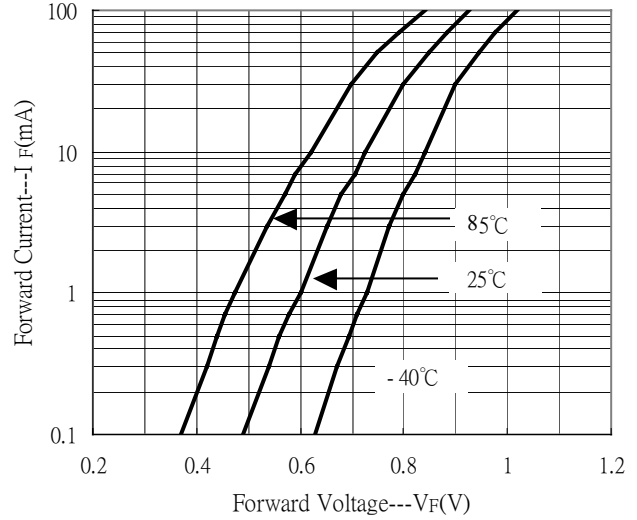
Characteristic	Symbol	Condition	Min.	Max.	Unit
Forward Voltage	VF	IF=100mA	-	1.2	V
Reverse Leakage Current	IR	VR=100V	-	0.1	μA
Diode Capacitance	CD	VR=0.5V, f=1MHz	-	3	pF
Reverse Recovery Time	trr	IF=IR=10mA	-	4	ns

Typical Characteristics

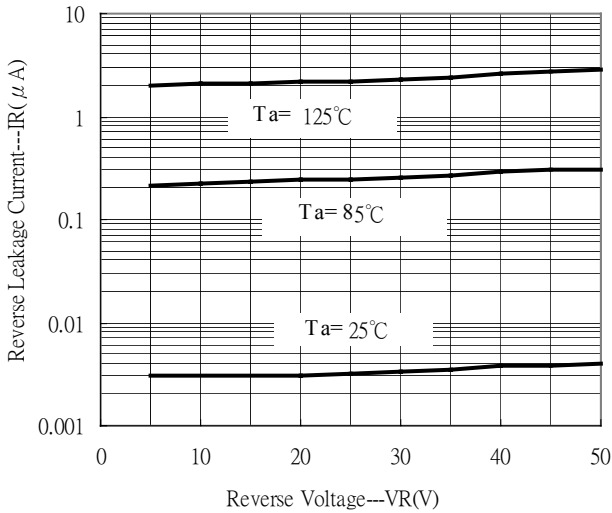
Forward Current Derating Curve



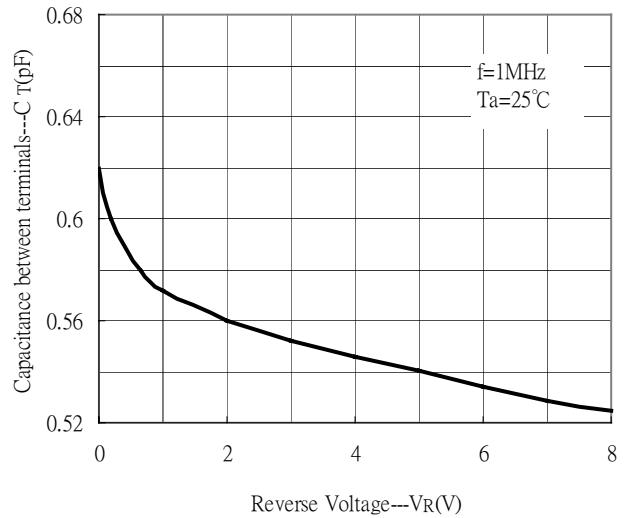
Forward Current vs Forward Voltage



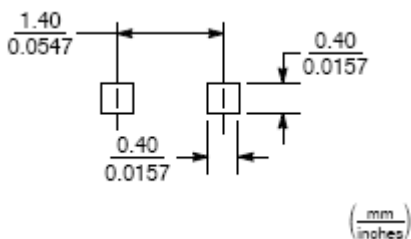
Reverse Leakage Current vs Reverse Voltage



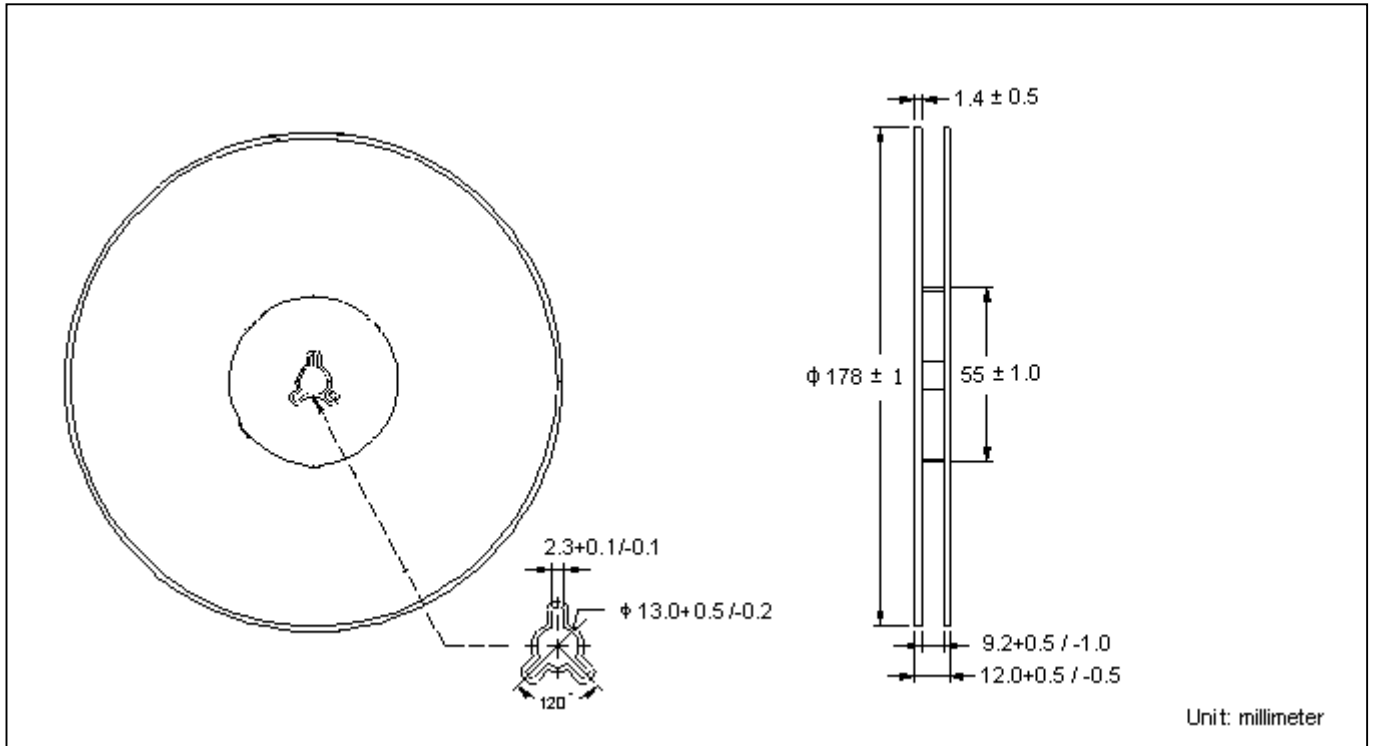
Capacitance vs Reverse Voltage



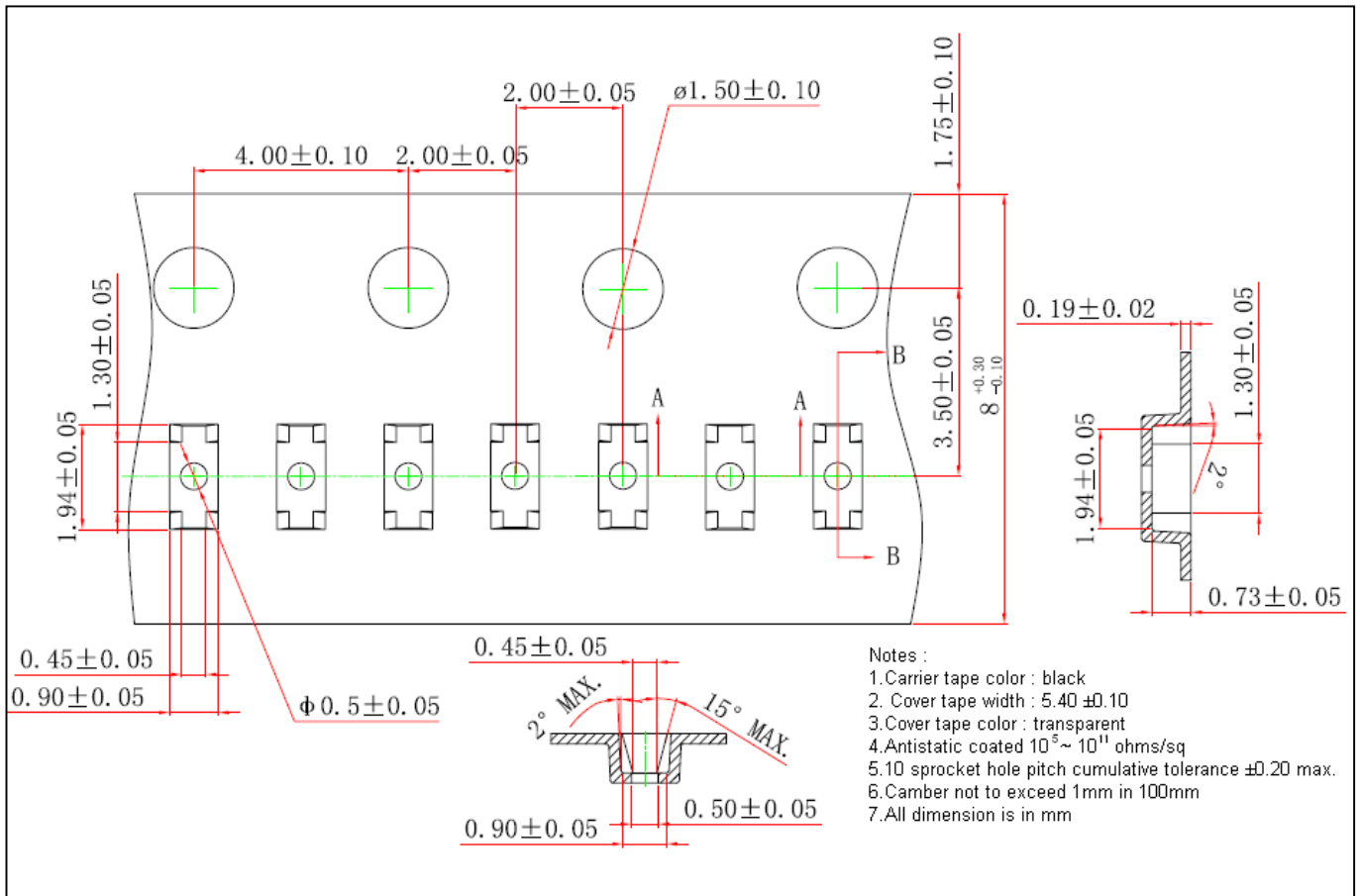
Recommended Footprint



Reel Dimension



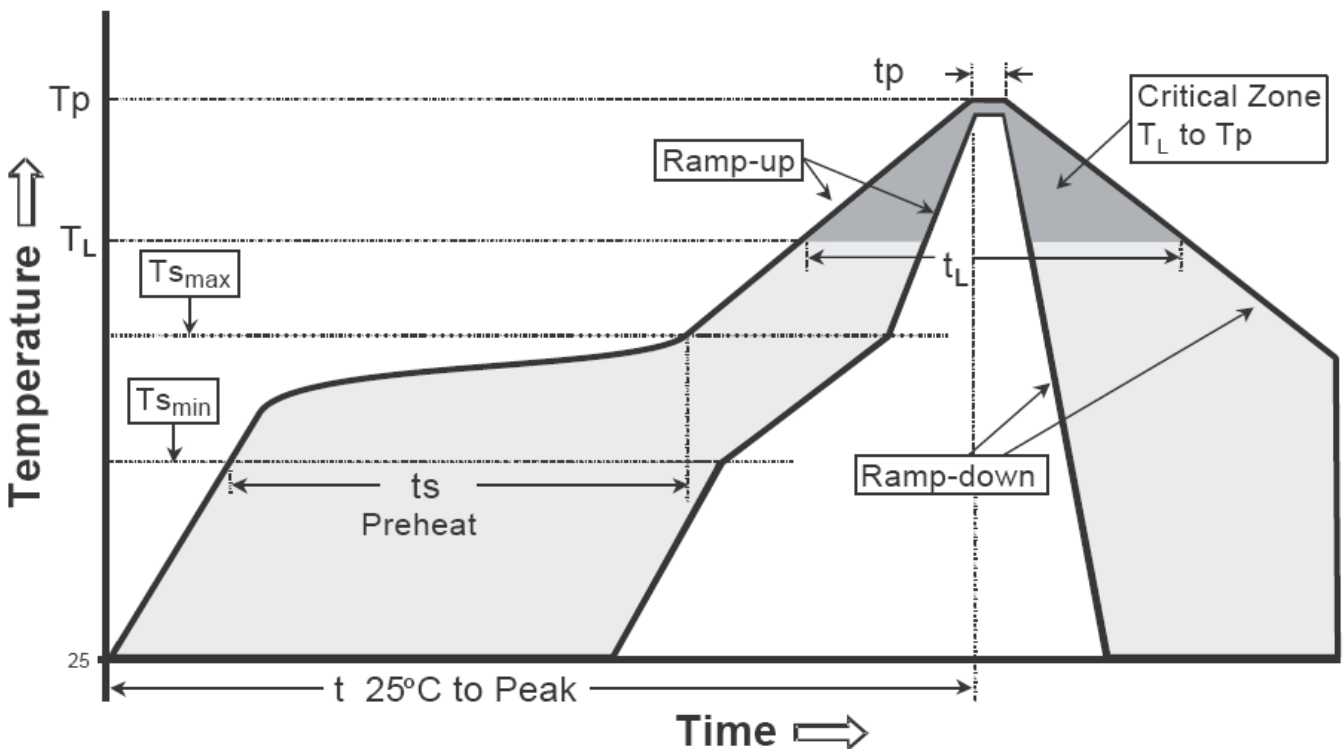
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

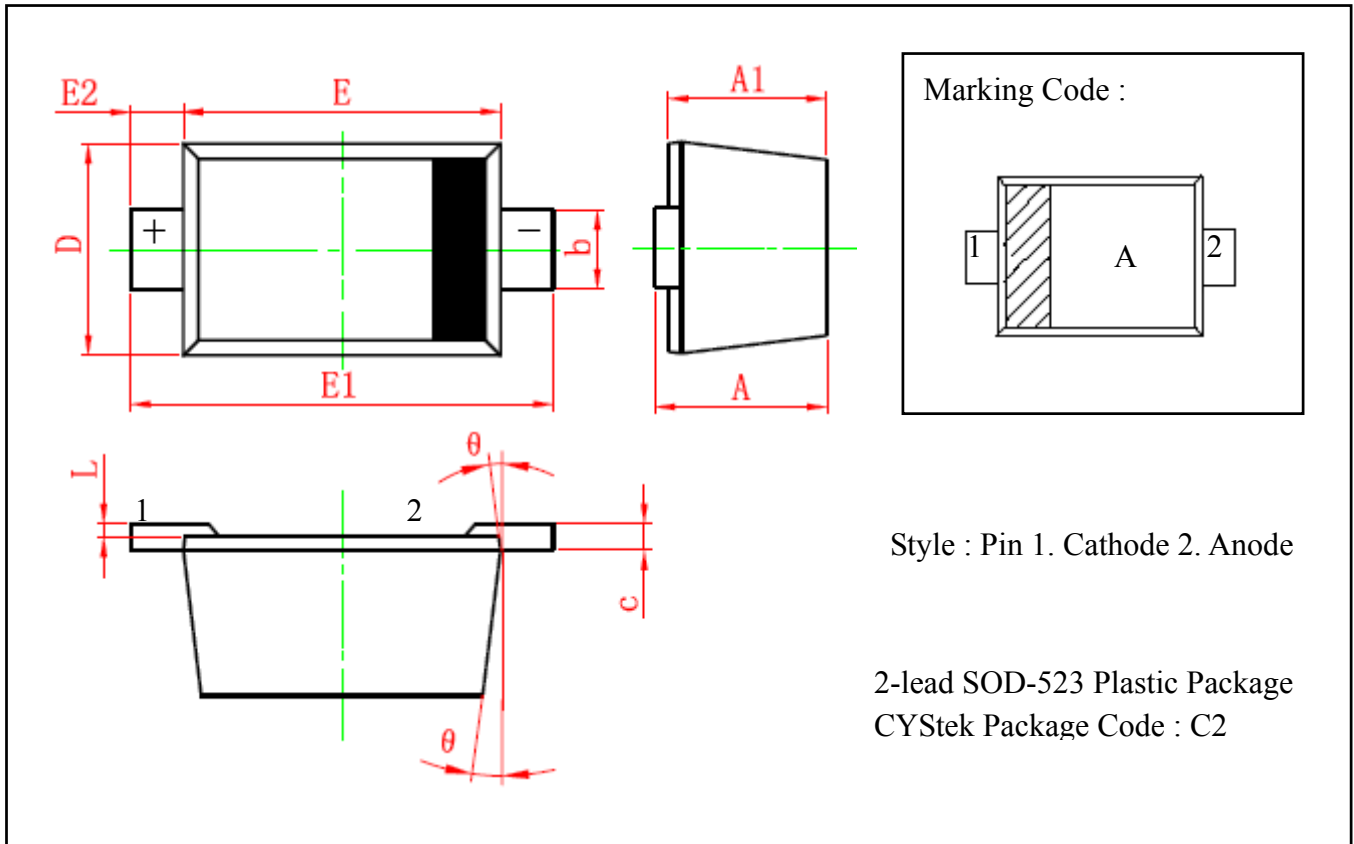
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(T _{s min})	100°C	150°C
-Temperature Max(T _{s max})	150°C	200°C
-Time(t _{s min} to t _{s max})	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T _L)	183°C	217°C
- Time (t _L)	60-150 seconds	60-150 seconds
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOD-523 Dimension



*: Typical

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.510	0.770	0.020	0.031	E	1.100	1.300	0.043	0.051
A1	0.500	0.700	0.020	0.028	E1	1.500	1.700	0.059	0.067
b	0.250	0.350	0.010	0.014	E2	0.200	REF	0.008	REF
c	0.080	0.150	0.003	0.006	L	0.010	0.070	0.001	0.003
D	0.750	0.850	0.030	0.033	θ	7°	REF	7°	REF

Notes: 1. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 2. If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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